

IMPROVEMENT IN INJECTION MOLDING APPARATUS

ABSTRACT

5 An integrated circuit encapsulation apparatus comprises a molding press, which has a mold defining a cavity adapted to receive an integrated circuit die and an attached leadframe for encapsulation thereof. The press is provided with an integrated mold brushing unit which has transversely rotating brushes and travels over the mold faces to remove debris. In a further refinement, a spring-loaded bearing system is provided for easy removal of the mold.

10

Figure 2

This Sheet Has Been Replaced

